



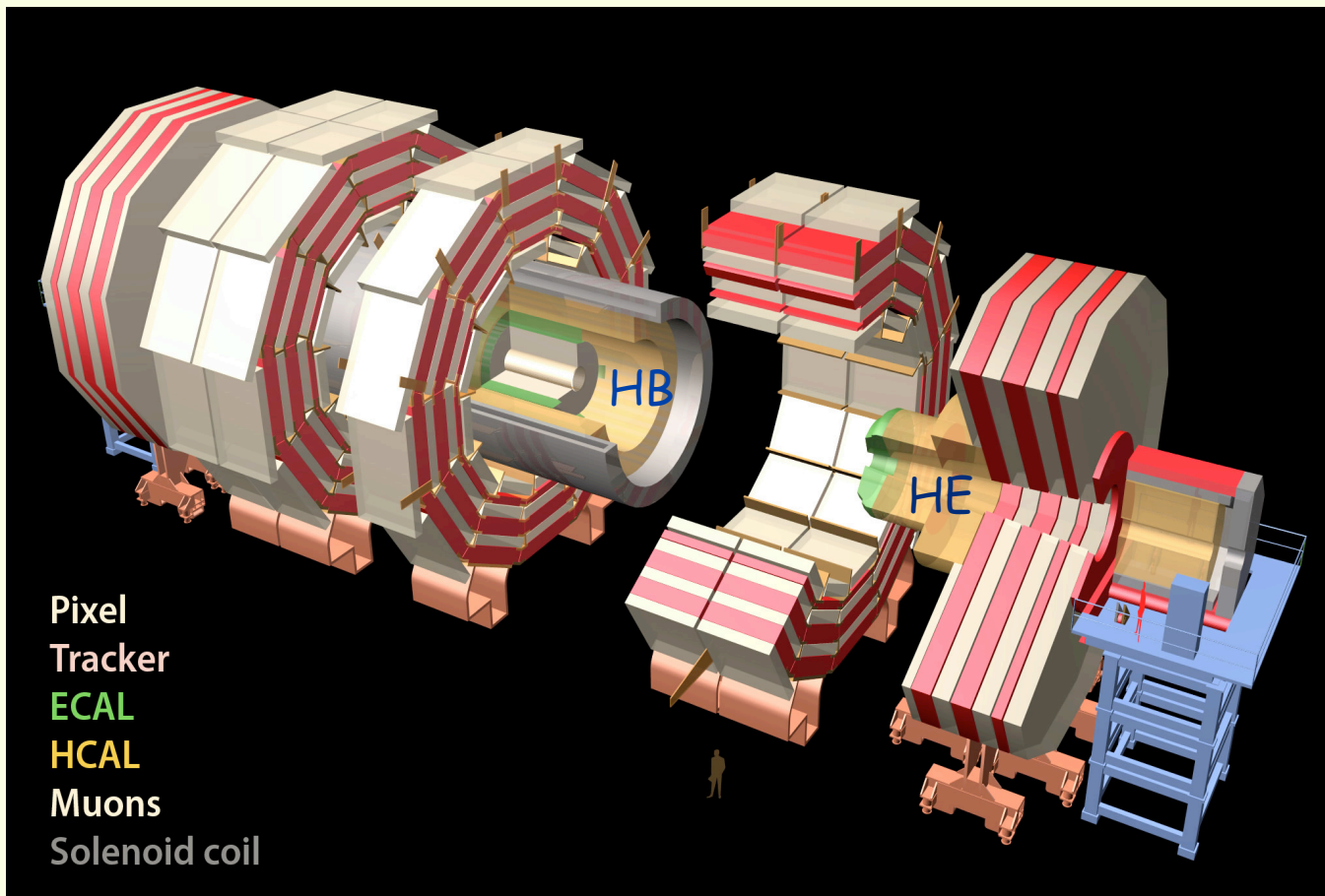
# **CMS HCAL Upgrade Plans using G-APDs**

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**On behalf of the CMS HCAL Collaboration**



# CMS Hadronic Calorimeter



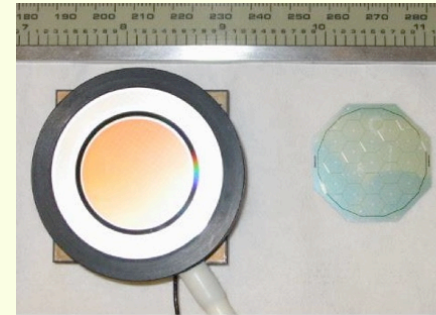
Barrel and Endcap are inside the 4 Tesla magnetic field



# HPD replacement with G-APDs in HO

HPD is the base line photo detector for the CMS HCAL

- PMTs can not operate in high magnetic field
- Low light yield /GeV in the HCAL
- High dynamic range



Now widely available G-APDs

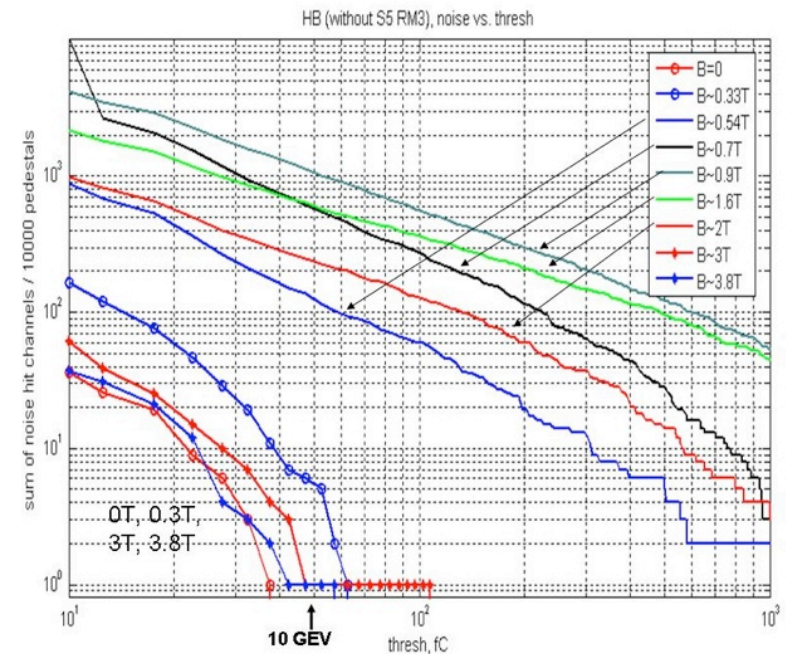
PDE: HPD 12% vs G-APD 30% at 520nm

Operation voltage: 8kV vs 90V

G-APD disadvantage:

Temperature dependence

Noise in HPD due to SEA in the fringe fields

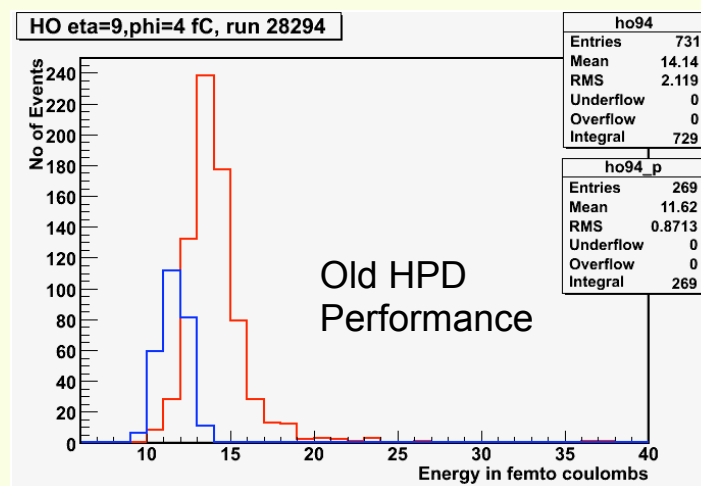
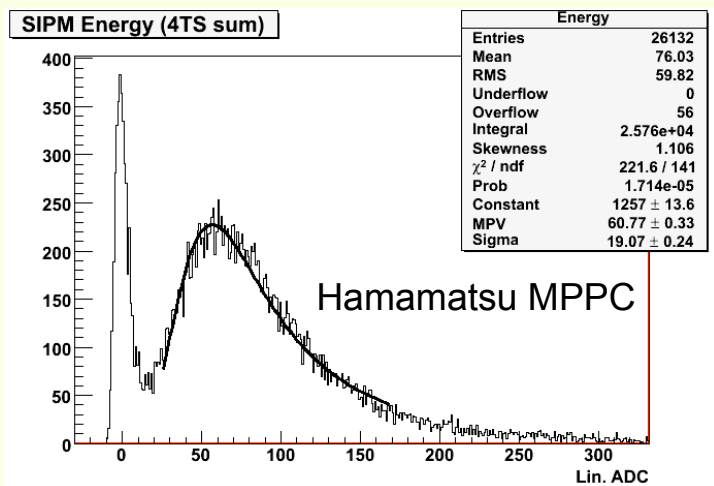
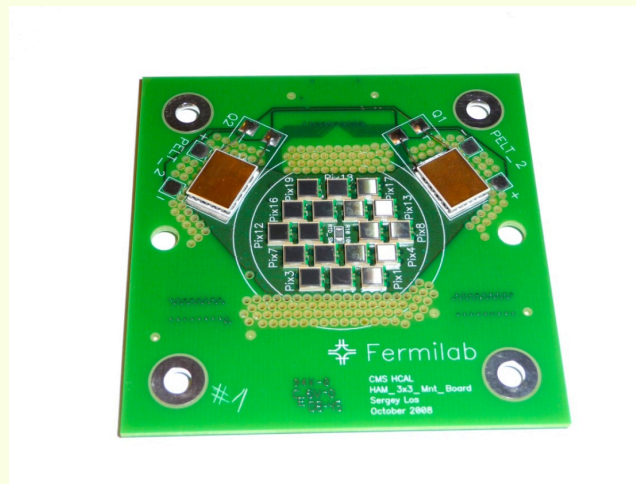




# Hcal Outer (HO) replacement

144 G-APDs installed into CMS  
 in April 2009 and now operating.  
 36 Zecotek 15K/mm<sup>2</sup> 3X3mm,  
 108 Hamamatsu 400/mm<sup>2</sup> 3X3mm.

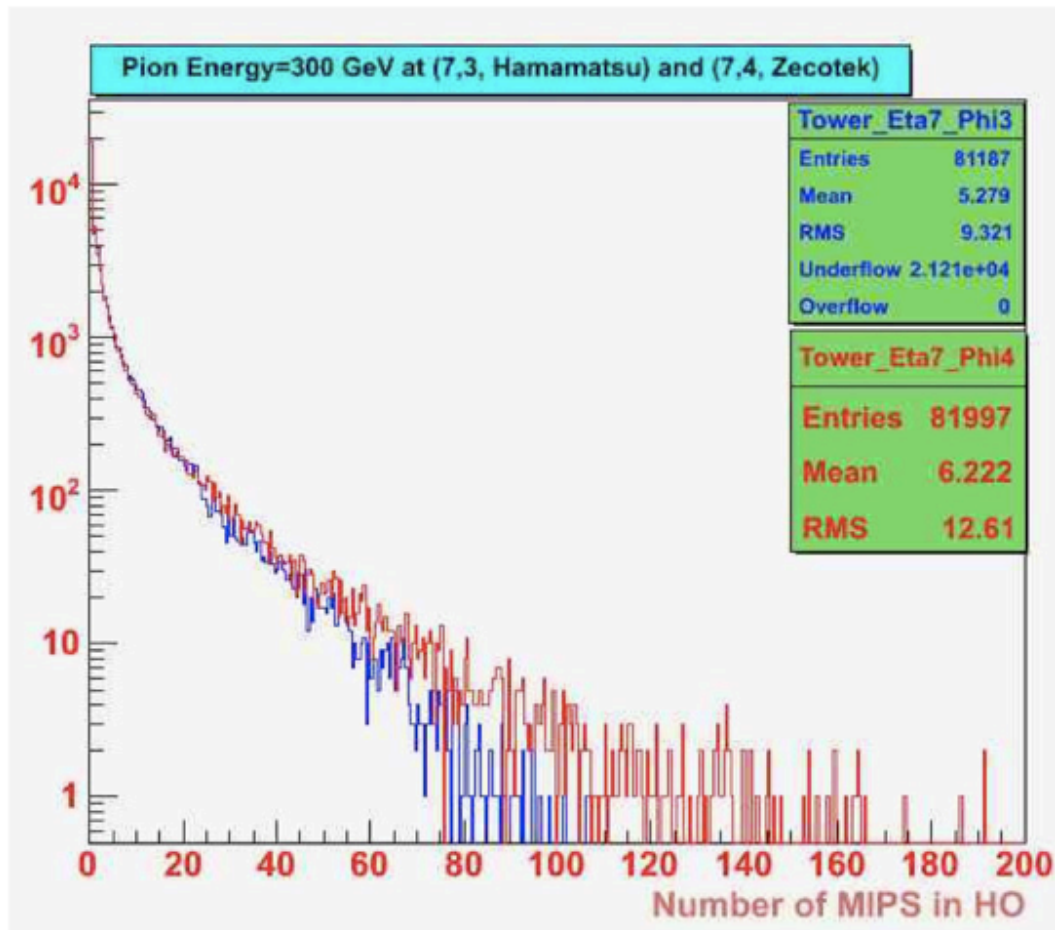
Install ALL HO (~2500 channels)  
 in next shutdown





# Small saturation

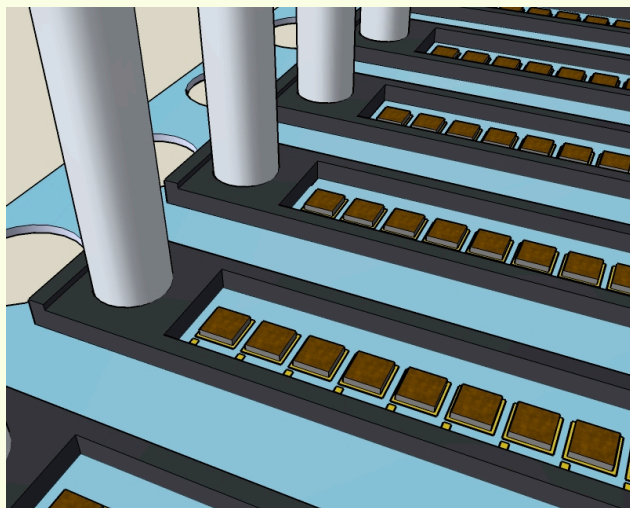
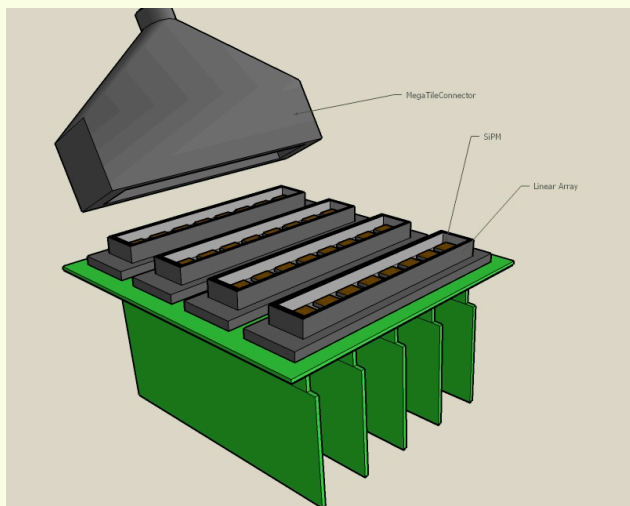
Zecotek/Hamamatsu response to 300 GeV Pions in HO at Eta=7



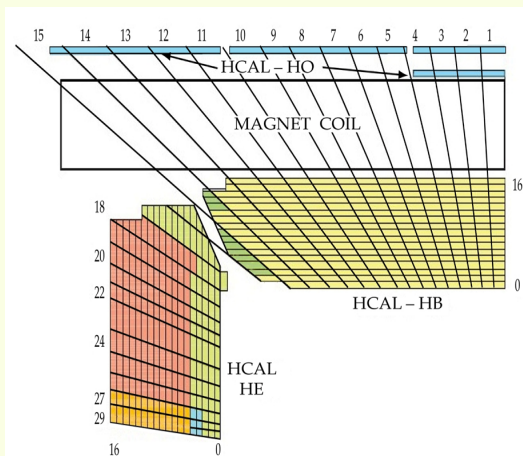




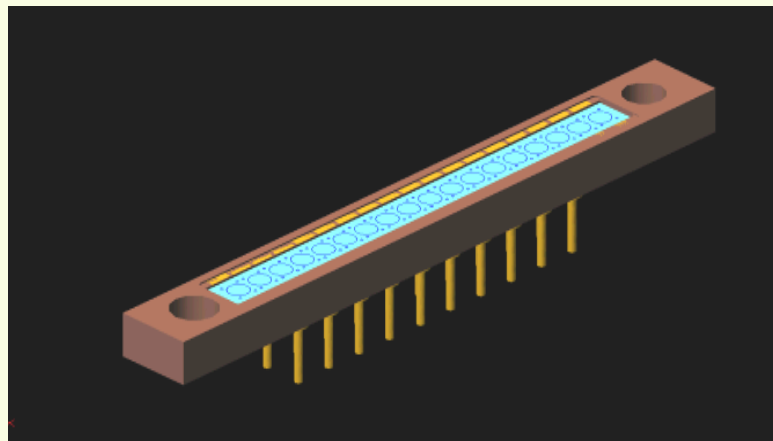
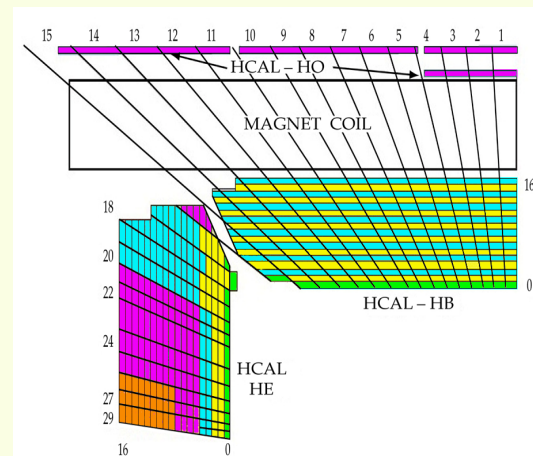
# Hcal Barrel/Endcap (HB/HE)



18 Channel RMs



48 Channel HB RMs  
32 Channel HE RMs





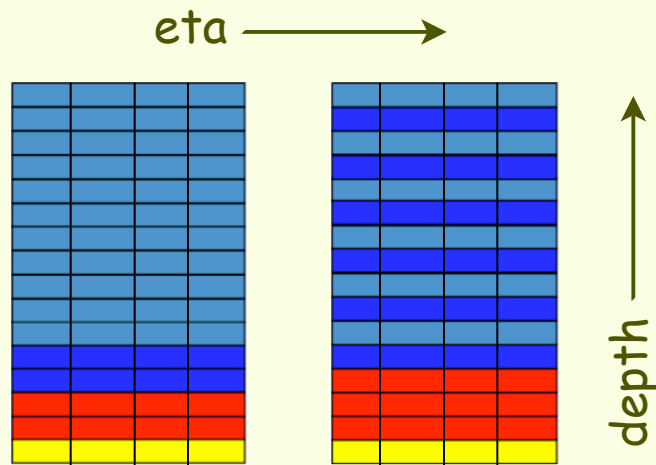
# G-APD improvement vs HPD

HPD readout => no segmentation

But fibers are coming from each layer and summed into 1 HPD pixel

PDE: HPD 12% vs G-APD 30% at 520nm  
Operation voltage: 8kV vs 90V

disadvantage: Temperature dependence



proposed HCAL towers

Goal is 4 depth segments:

(a) maximizes resolution by concentrating layers where the energy density is highest

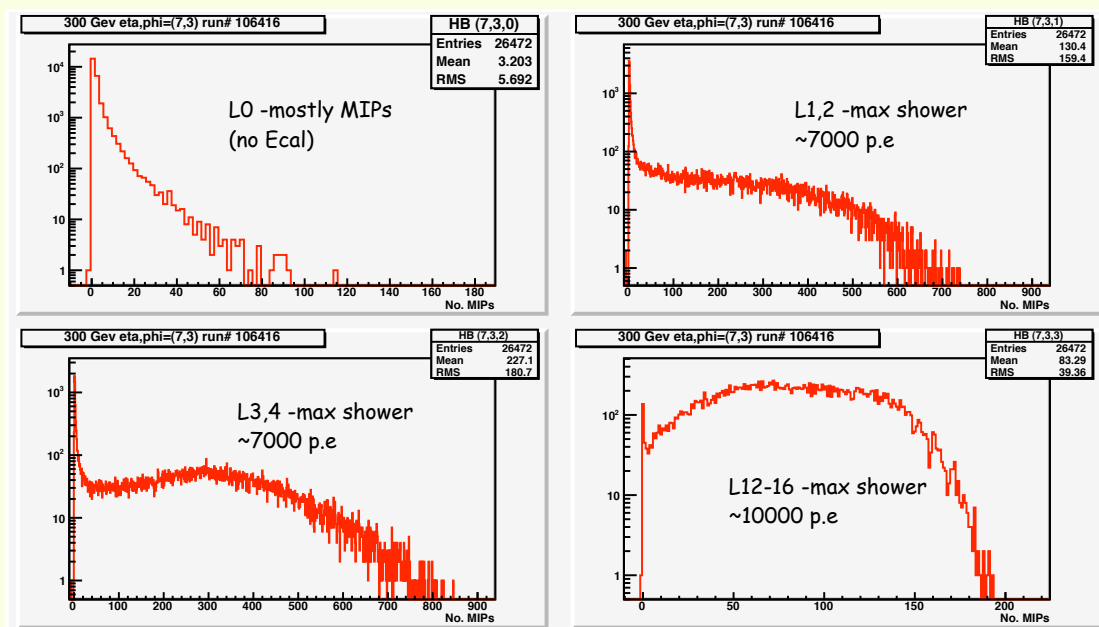
(b) adds redundancy and robustness



# Challenges using G-APDs in HCAL

- 1) Very large dynamic range  
A few p.e. /MIP/layer = 2 GeV up to 500 GeV in a few layer from Jet events
- 2) High occupancy in front layers in SLHC  
Fast recovery time

## 300 GeV pion distributions vs depth in CMS HCAL tower (No ECAL)

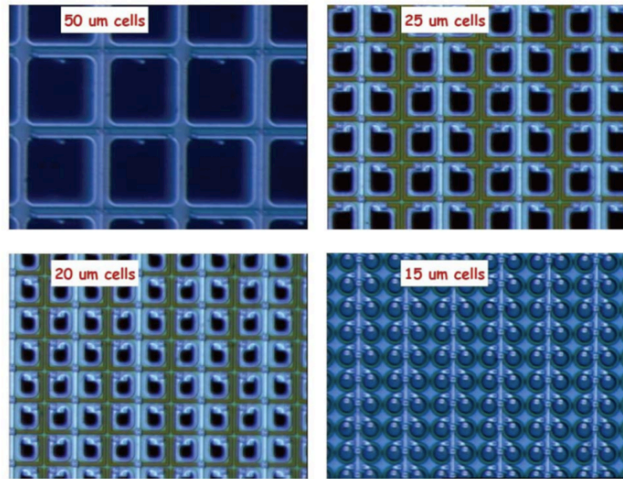


- 3) Radiation hard up to  $3E12$  1 MeV neutrons/cm<sup>2</sup> for 3000 fb<sup>-1</sup> (SLHC)

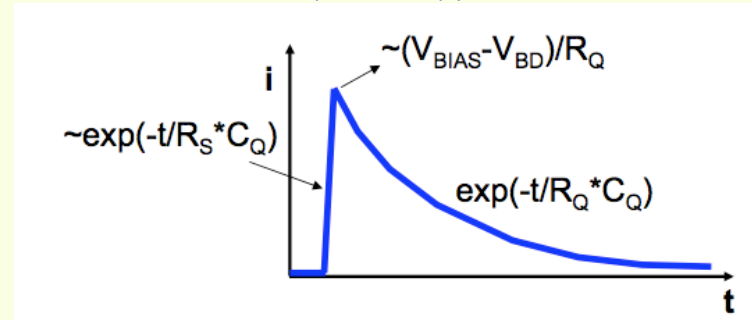




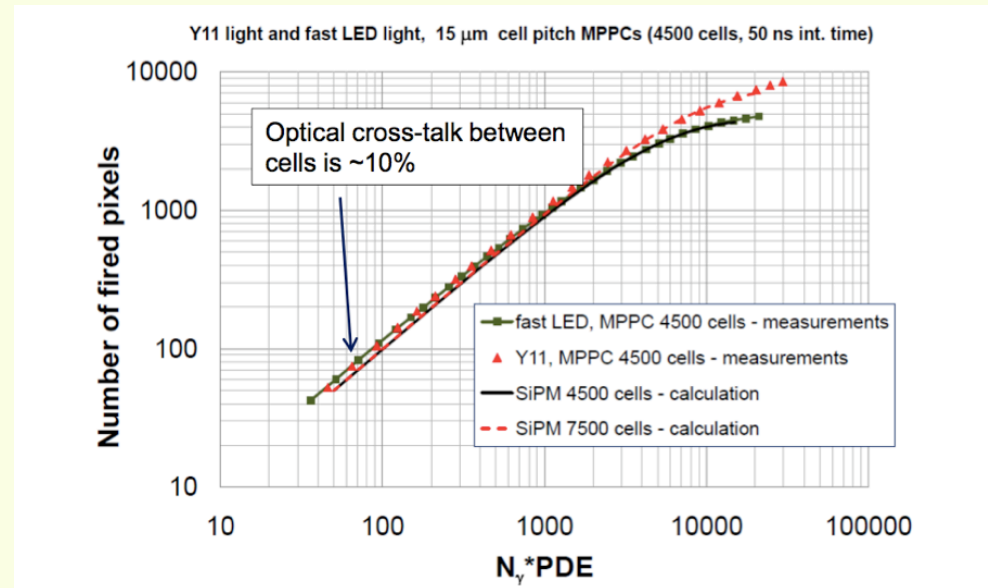
# Hamamatsu small cell R&D 2010



## Cell recovery for Typical G-APD



## Dynamic range increase due to fast cell recovery

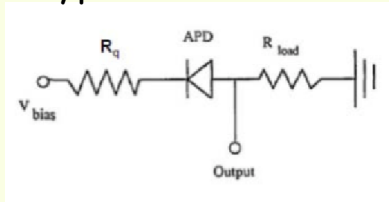


- 1)  $R_q$  is typically 300 kohm (min)
- 2) R&D wafers from 2009 show  $C_d$  (15 micron) =  $\sim 10$  fF

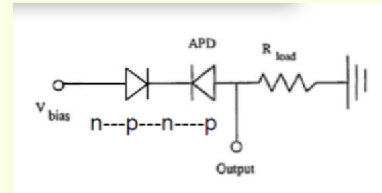


# “VHD” MAPD from Zecotek

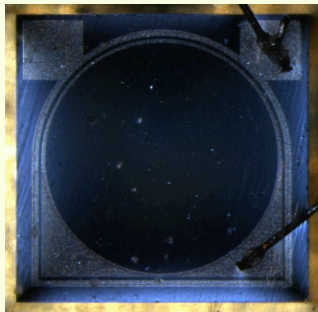
Typical G-APD cell



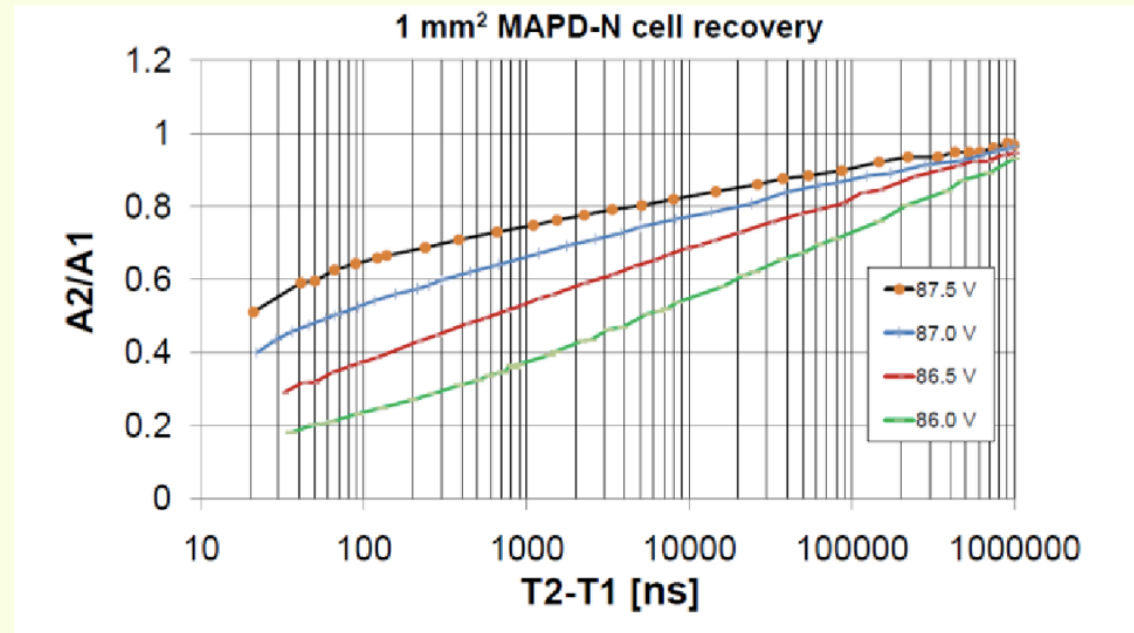
Zecotek MAPD cell



Zecotek (15000 cells/mm<sup>2</sup>)



internal  $R_q$   
G.F.= high  
PDE= 30%

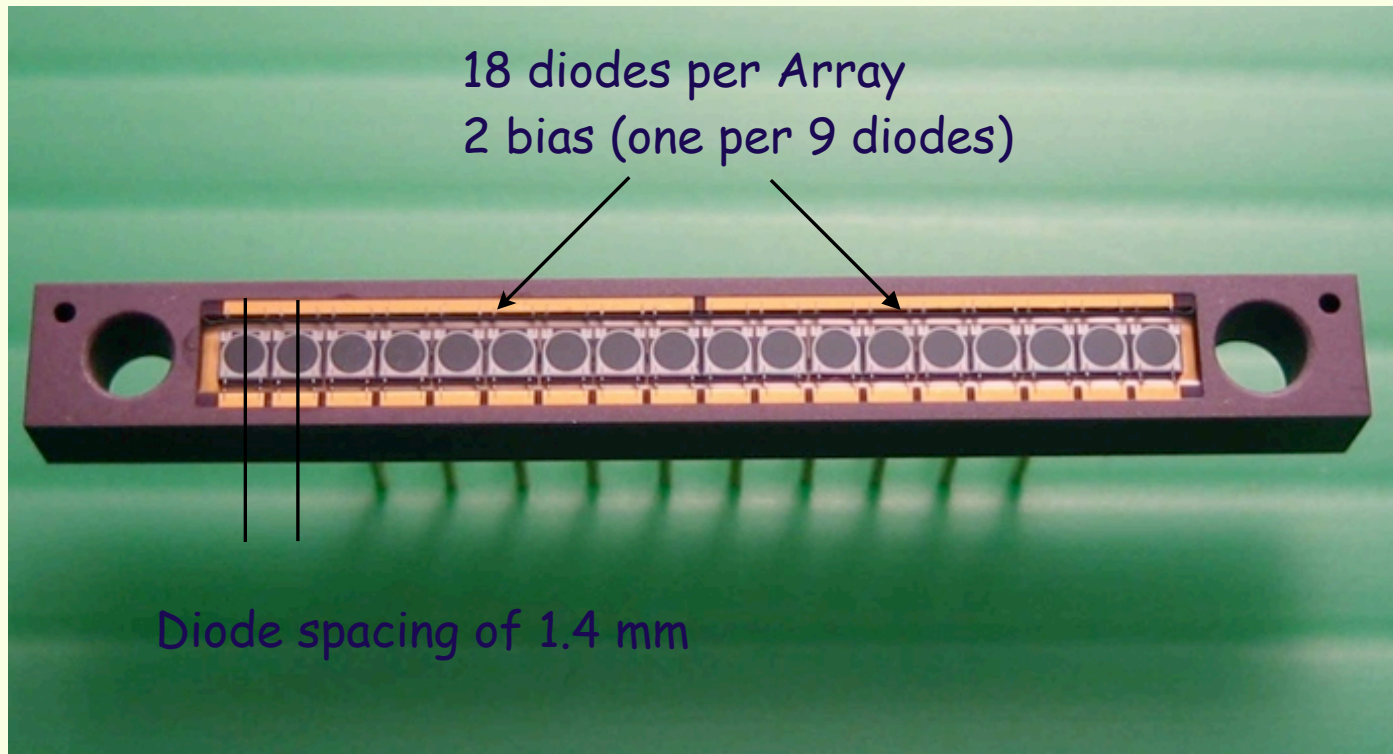


- R&D wafers “on the way” to reduce recovery time !



# 18 channel MAPD Array

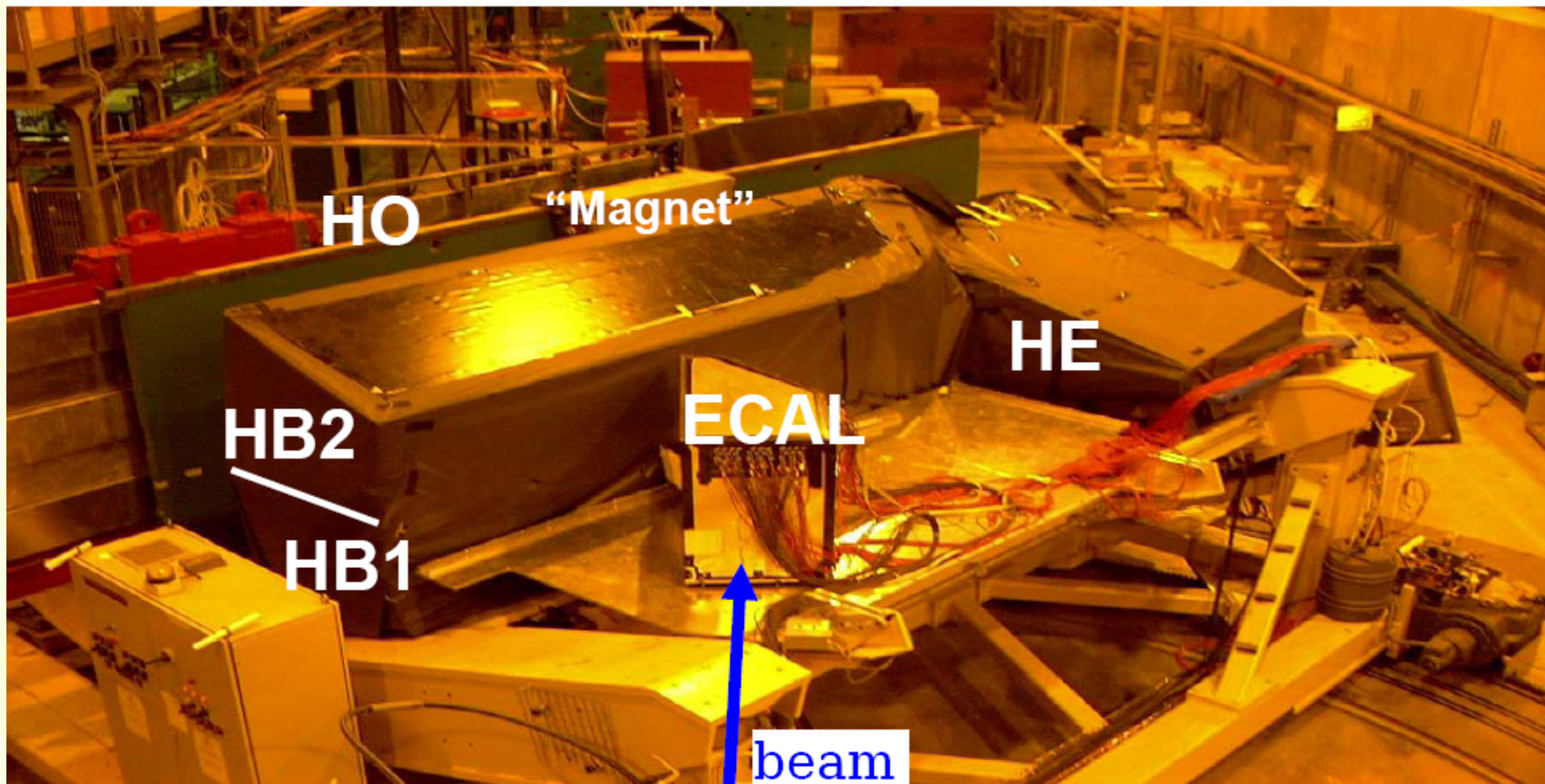
CERN: 20 pin package by Kyocera (fine Ceramics, Germany)  
MAPD assembly and potting at Zecotek



**Total diodes needed = 100k  $\approx$  5000 Arrays**



# CERN H2 Test Beam Setup up to 300 GeV

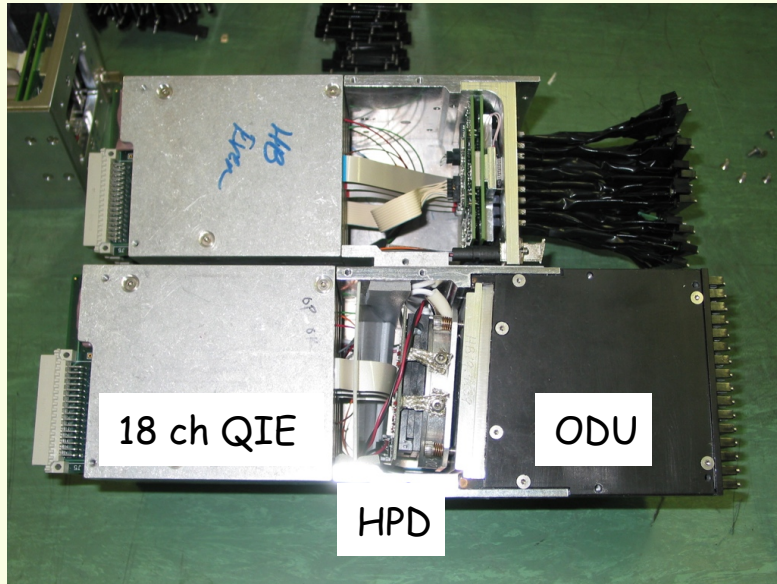


This year we expect real ECAL Supermodule and good data on the advantages of the depth segmentation.

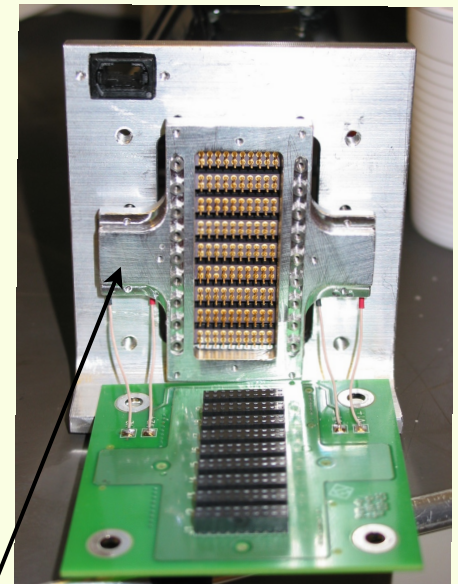
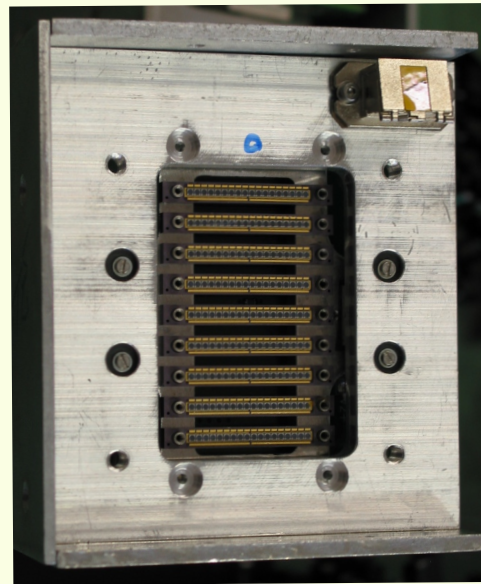




# Prototype Module

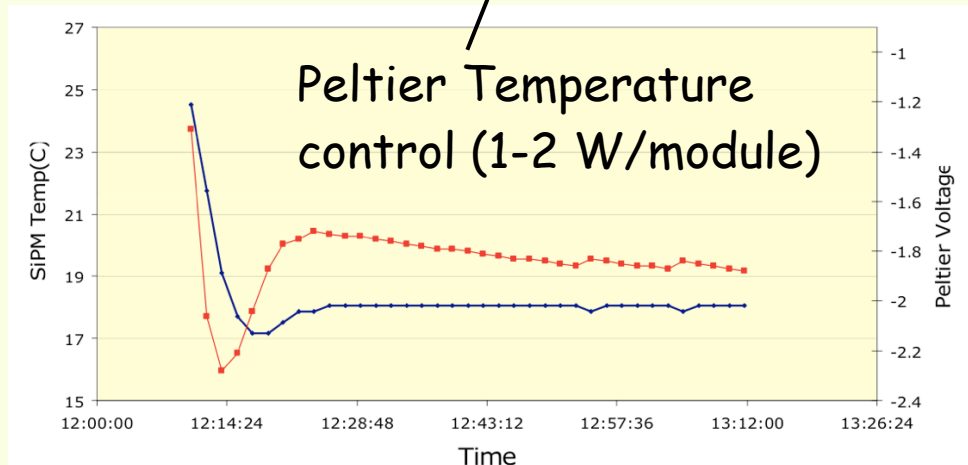


Bottom: HCAL HPD R-Module  
Top: GAPD R-Module



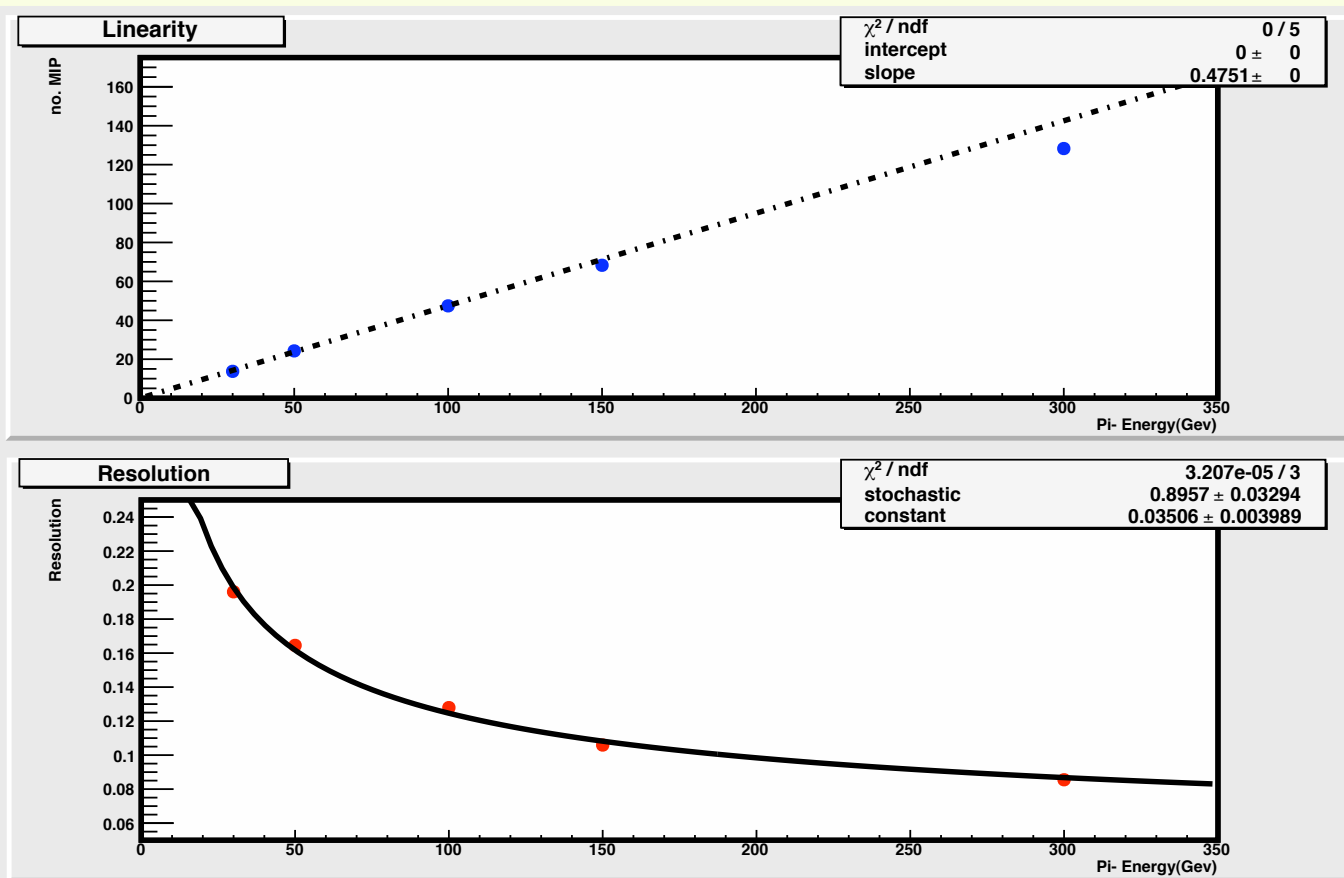
4 modules = 4x9 = 36 Arrays

eta, phi, depth coverage = 4x4x4





# 2009 TB data with 15k cells/mm<sup>2</sup> array's



Repeat measurement in 2011 with fast HPK and other companies

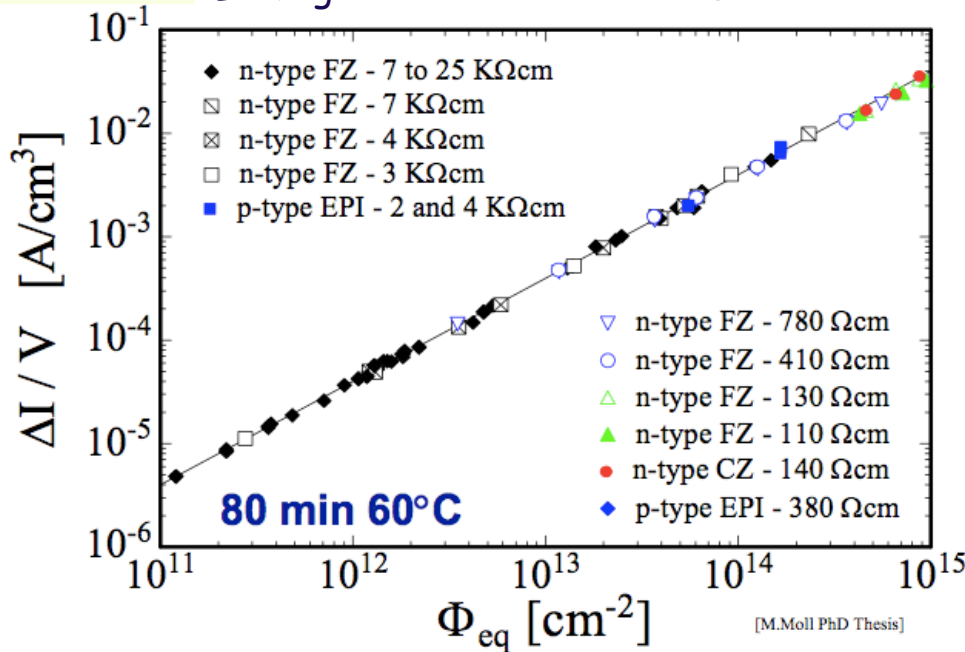




# GM-APD Radiation Damage

Leakage current increase in Si-PIN diodes

eq. 1 Mev neutrons



Similar damage seen in GM-APDs

slope= 4E-17 A/cm

V= cell size \* d<sub>epi</sub> (few microns)

Due to high gain we can see the current increase in Si as single p.e. counts:

$$\text{Dark Count} = 1/q * V * \Phi * \text{slope} * G.F. * P_{(v)}$$

high dose ==> MHz noise /cell



# Amplitude during irradiation

230 MeV proton radiation at  
Massachusetts General Hospital in 2008

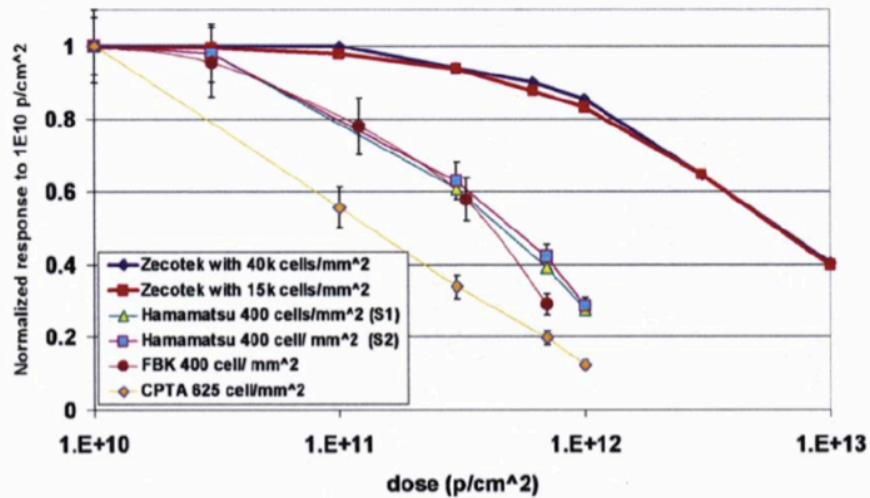
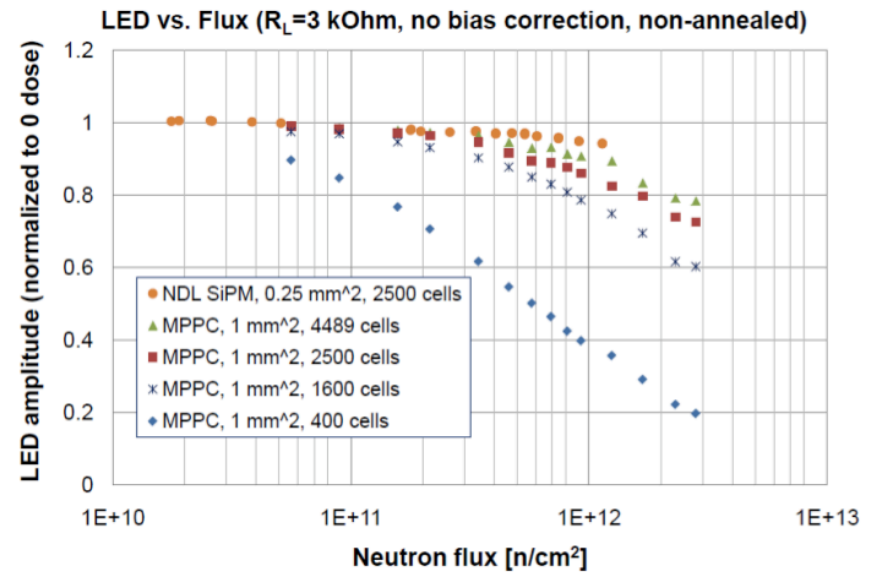


Fig.11. Response vs. radiation fluence for different samples and manufacturers (gain was corrected for voltage drop over the series resistor).

24 GeV backscattered protons  
(neutrons) radiation at CERN PS 2010





# Conclusion

Great improvements have been made in the development of silicon based small cell size SiPMs or GAPDs.

More companies have shown interest in making large dynamic range devices. Also samples from: FBK (Italy), Ketek (Germany), NDL (China), CPTA (Russia)

R&D will continue to study these devices for operation in CMS SLHC.